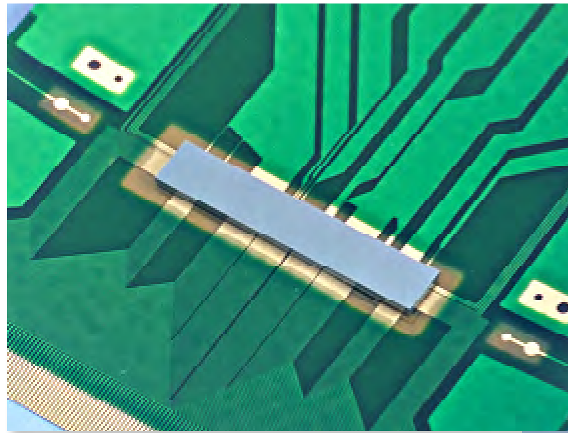
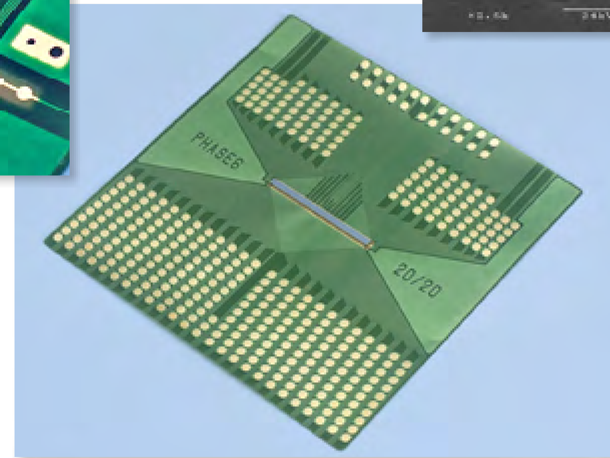
SoundBonding application

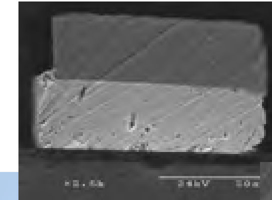
〈Flip-Chip Bonding〉

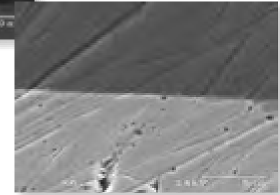
Semiconductor / SoundBonding of Multiple Electrodes Bump

SH50MPi Flip chip bonding Semi-automatic system









(Magnified bonded cross section)

Chip size ; 20.05 x 1.06 x 0.42 mm
Chip bump ; Au plated 770 pins
Bump pitch ; 40 (30) μm
Substrate ; Au plated pads on 2 layers of film

SoundPower® Laboratory

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